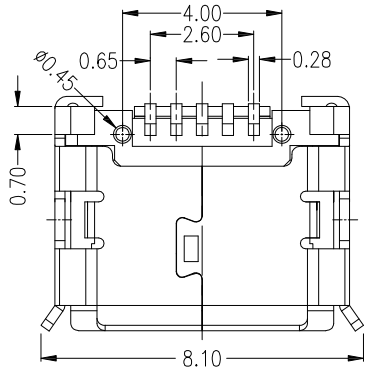
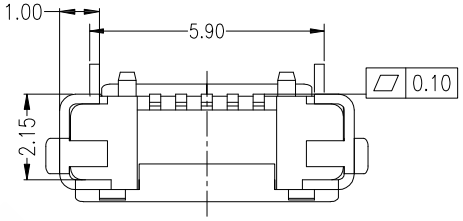
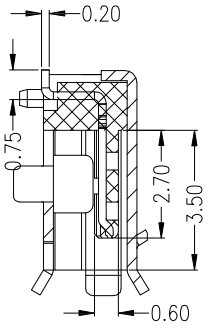
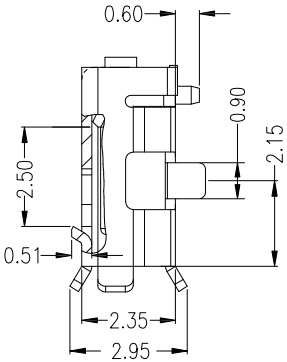
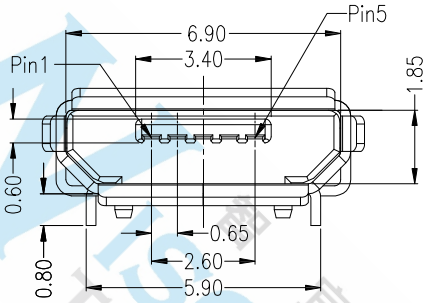
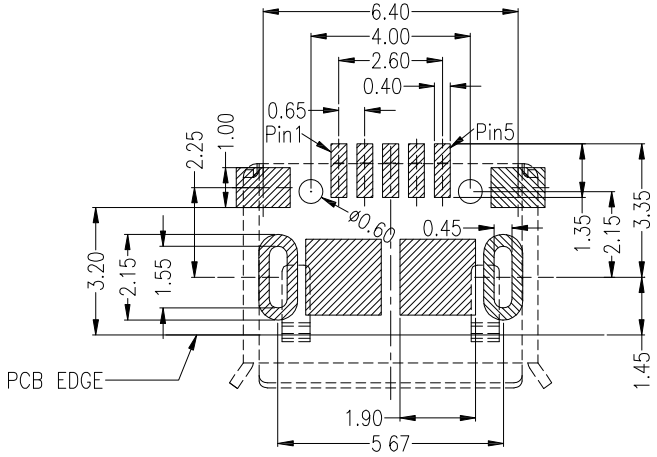




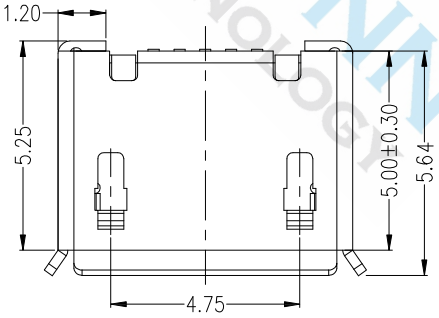








P.C.B LAYOUT MOUNTING PATTERN



NOTES:

MATERIAL:

1.1 HOUSING: LCP, UL94V-0

1.2 CONTACT: PHOSPHOR BRONZE

1.3 SHELL: BRASS

Finish:

2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL

2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER OR
TIN UNDER PLATED SURFACE LAYER

3.SPECIFICATION:

3.1 CURRENT RATING: 1.0 A MAX

3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 V(ac) FOR 1min

3.3 CONTACT RESISTANCE: 30 mΩ MAX.

3.4 INSULATION RESISTANCE: 100 MΩ MIN.

3.5 TOTAL MATING FORCE: 3.57 Kgf MAX.

3.6 TOTAL UNMATING FORCE: 1.0 Kgf MIN.

3.7 TEMPERATURE RANGE: -30℃ ~ +80℃

WISCONN TECHNOLOGY

DIMENSIONS TOLERANCE METRIC									
Up to 5 ±0.2 Above 5~15 ±0.3 Above 15~30 ±0.4 Above 30~50 ±0.5 Angle ±0.3°	單位(UNITS)	MM	處理(FINISH)	SEE NOTE	審校(CH'K)	Calvin	圖名(NAME)	MICRO USB2.0 B TYPE R/A SMT+DIP 5.65mm 4.0柱	WISCONN Technology Co.,Ltd Tel:02-2790-1979 Fax:02-2790-1569
	數量(QT'Y)	N/A	繪圖(DRAW)	Johnson	核准(APP'D)	Selena	料號(PART NUMBER)	WMRU2-5-xxR3D1P3	
	材料(MT'L)	SEE NOTE	設計(DE'N)	Mike	日期(DATE)	SEP.06.2017	圖號(DRAW NUMBER)	T002	比例(SCALE) 1/1 圖紙(SIZE) A4 頁次(SHEET) 1 版次(REV.) A
							圖檔(FILE NAME .DWG)		